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What are **Embedded - System On Chip (SoC)**?

**System On Chip (SoC)** integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details	
Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	256KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I <sup>2</sup> C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	1.5GHz
Primary Attributes	FPGA - 570K Logic Elements
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA, FC (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10as057k3f35e2lg

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



# **Contents**

Inte	I <sup>®</sup> Arria <sup>®</sup> 10 Device Overview	3
	Key Advantages of Intel Arria 10 Devices	4
	Summary of Intel Arria 10 Features	
	Intel Arria 10 Device Variants and Packages	7
	Intel Arria 10 GX	7
	Intel Arria 10 GT	. 11
	Intel Arria 10 SX	. 14
	I/O Vertical Migration for Intel Arria 10 Devices	. 17
	Adaptive Logic Module	
	Variable-Precision DSP Block	. 18
	Embedded Memory Blocks	. 20
	Types of Embedded Memory	21
	Embedded Memory Capacity in Intel Arria 10 Devices	21
	Embedded Memory Configurations for Single-port Mode	
	Clock Networks and PLL Clock Sources	. 22
	Clock Networks	
	Fractional Synthesis and I/O PLLs	
	FPGA General Purpose I/O	
	External Memory Interface	
	Memory Standards Supported by Intel Arria 10 Devices	
	PCIe Gen1, Gen2, and Gen3 Hard IP	
	Enhanced PCS Hard IP for Interlaken and 10 Gbps Ethernet	
	Interlaken Support	
	10 Gbps Ethernet Support	
	Low Power Serial Transceivers	
	Transceiver Channels	
	PMA Features	
	PCS Features	
	SoC with Hard Processor System	
	Key Advantages of 20-nm HPS	
	Features of the HPS	
	FPGA Configuration and HPS Booting	37
	Hardware and Software Development	
	Dynamic and Partial Reconfiguration	
	Dynamic Reconfiguration	
	Partial Reconfiguration	
	Enhanced Configuration and Configuration via Protocol	
	SEU Error Detection and Correction	
	Power Management	
	Incremental Compilation	
	Document Revision History for Intel Arria 10 Device Overview	40



# Intel® Arria® 10 Device Overview

The Intel® Arria® 10 device family consists of high-performance and power-efficient 20 nm mid-range FPGAs and SoCs.

Intel Arria 10 device family delivers:

- Higher performance than the previous generation of mid-range and high-end FPGAs.
- Power efficiency attained through a comprehensive set of power-saving technologies.

The Intel Arria 10 devices are ideal for high performance, power-sensitive, midrange applications in diverse markets.

Table 1. Sample Markets and Ideal Applications for Intel Arria 10 Devices

Market	Applications
Wireless	Channel and switch cards in remote radio heads     Mobile backhaul
Wireline	<ul> <li>40G/100G muxponders and transponders</li> <li>100G line cards</li> <li>Bridging</li> <li>Aggregation</li> </ul>
Broadcast	<ul> <li>Studio switches</li> <li>Servers and transport</li> <li>Videoconferencing</li> <li>Professional audio and video</li> </ul>
Computing and Storage	Flash cache     Cloud computing servers     Server acceleration
Medical	Diagnostic scanners     Diagnostic imaging
Military	Missile guidance and control     Radar     Electronic warfare     Secure communications

#### **Related Information**

Intel Arria 10 Device Handbook: Known Issues

Lists the planned updates to the *Intel Arria 10 Device Handbook* chapters.

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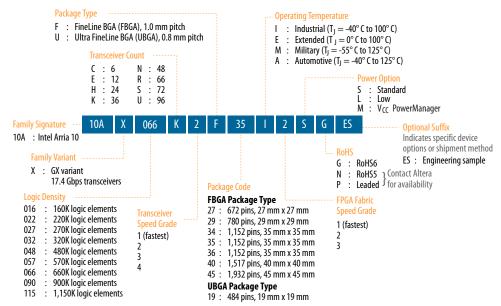
Feature		Description			
Low-power serial transceivers	- Intel Arria 10 GX - Intel Arria 10 GT-  Backplane support: - Intel Arria 10 GX Intel Arria 10 GT-  Extended range dow  ATX transmit PLLs w  Electronic Dispersion module  Adaptive linear and of  Transmitter pre-emp	Intel Arria 10 GX—up to 12.5 Intel Arria 10 GT—up to 12.5 Intel Arria 10 GX—up to 12.5 Intel Arria 10 G			
HPS (Intel Arria 10 SX devices only)	Processor and system	Dual-core ARM Cortex-A9 MPCore processor—1.2 GHz CPU with 1.5 GHz overdrive capability  256 KB on-chip RAM and 64 KB on-chip ROM  System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers  Security features—anti-tamper, secure boot, Advanced Encryption Standard (AES) and authentication (SHA)  ARM CoreSight* JTAG debug access port, trace port, and on-chip trace storage			
	External interfaces	Hard memory interface—Hard memory controller (2,400 Mbps DDR4, and 2,133 Mbps DDR3), Quad serial peripheral interface (QSPI) flash controller, NAND flash controller, direct memory access (DMA) controller, Secure Digital/MultiMediaCard (SD/MMC) controller     Communication interface— 10/100/1000 Ethernet media access control (MAC), USB On-The-GO (OTG) controllers, I²C controllers, UART 16550, serial peripheral interface (SPI), and up to 62 HPS GPIO interfaces (48 direct-share I/Os)			
	Interconnects to core	High-performance ARM AMBA* AXI bus bridges that support simultaneous read and write HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa Configuration bridge that allows HPS configuration manager to configure the core logic via dedicated 32-bit configuration port FPGA-to-HPS SDRAM controller bridge—provides configuration interfaces for the multiport front end (MPFE) of the HPS SDRAM controller			
Configuration	Enhanced 256-bit ad	comprehensive design protection to protect your valuable IP investments dvanced encryption standard (AES) design security with authentication obtocol (CvP) using PCIe Gen1, Gen2, or Gen3			
		continued			

 $<sup>^{(2)}</sup>$  Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



#### **Available Options**

Figure 1. Sample Ordering Code and Available Options for Intel Arria 10 GX Devices



#### **Related Information**

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.



#### **Maximum Resources**

Table 5. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 160, GX 220, GX 270, GX 320, and GX 480)

Resc	ource			<b>Product Line</b>		
		GX 160	GX 220	GX 270	GX 320	GX 480
Logic Elements	(LE) (K)	160	220	270	320	480
ALM		61,510	80,330	101,620	119,900	183,590
Register		246,040	321,320	406,480	479,600	734,360
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620
	MLAB	1,050	1,690	2,452	2,727	4,164
Variable-precision DSP Block		156	192	830	985	1,368
18 x 19 Multipli	er	312	384	1,660	1,970	2,736
PLL	Fractional Synthesis	6	6	8	8	12
	I/O	6	6	8	8	12
17.4 Gbps Trans	sceiver	12	12	24	24	36
GPIO (3)		288	288	384	384	492
LVDS Pair (4)		120	120	168	168	222
PCIe Hard IP Bl	ock	1	1	2	2	2
Hard Memory C	ontroller	6	6	8	8	12

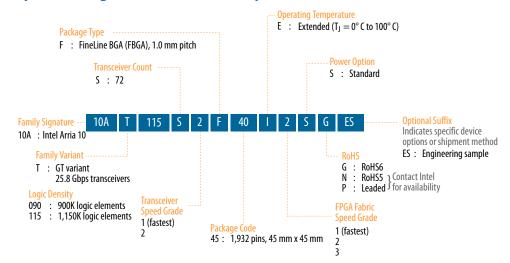
 $<sup>^{(3)}</sup>$  The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(4)</sup> Each LVDS I/O pair can be used as differential input or output.



#### **Available Options**

Figure 2. Sample Ordering Code and Available Options for Intel Arria 10 GT Devices





Product Line	duct Line U19 (19 mm × 19 mm, 484-pin UBGA)			F27 nm × 27 2-pin FB0			F29 nm × 29 )-pin FB0			F34 nm × 35 2-pin FB		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 480	_	_	_	_	_	_	48	312	12	48	444	24
SX 570	_	_	_	_	_	_	_	_	_	48	444	24
SX 660	_	_	_	_	_	_	_	_	_	48	444	24

#### Table 14. Package Plan for Intel Arria 10 SX Devices (F35, KF40, and NF40)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

<b>Product Line</b>	F35 (35 mm × 35 mm, 1152-pin FBGA)						NF40 (40 mm × 40 mm, 1517-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 270	48	336	24	_	_	_	_	_	_
SX 320	48	336	24	_	_	_	_	_	_
SX 480	48	348	36	_	_	_	_	_	_
SX 570	48	348	36	96	600	36	48	540	48
SX 660	48	348	36	96	600	36	48	540	48

#### **Related Information**

 ${\rm I/O}$  and High-Speed Differential  ${\rm I/O}$  Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

#### A10-OVERVIEW | 2018.04.09



Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resources
Medium precision fixed point	Two 18 x 19	1
High precision fixed or Single precision floating point	One 27 x 27	1
Fixed point FFTs	One 19 x 36 with external adder	1
Very high precision fixed point	One 36 x 36 with external adder	2
Double precision floating point	One 54 x 54 with external adder	4

#### Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	<b>Product Line</b>	Variable- precision DSP Block		nput and Output ons Operator	18 x 19 Multiplier Adder Sum Mode	18 x 18 Multiplier Adder
		DSP BIOCK	18 x 19 Multiplier	27 x 27 Multiplier		Summed with 36 bit Input
AIntel Arria 10	GX 160	156	312	156	156	156
GX	GX 220	192	384	192	192	192
	GX 270	830	1,660	830	830	830
	GX 320	984	1,968	984	984	984
	GX 480	1,368	2,736	1,368	1,368	1,368
	GX 570	1,523	3,046	1,523	1,523	1,523
	GX 660	1,687	3,374	1,687	1,687	1,687
	GX 900	1,518	3,036	1,518	1,518	1,518
	GX 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 GT	GT 900	1,518	3,036	1,518	1,518	1,518
GI	GT 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10	SX 160	156	312	156	156	156
SX	SX 220	192	384	192	192	192
	SX 270	830	1,660	830	830	830
						continued



## **Types of Embedded Memory**

The Intel Arria 10 devices contain two types of memory blocks:

- 20 Kb M20K blocks—blocks of dedicated memory resources. The M20K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide and shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Intel Arria 10 devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

## **Embedded Memory Capacity in Intel Arria 10 Devices**

Table 18. Embedded Memory Capacity and Distribution in Intel Arria 10 Devices

	Product		M20K		MLAB		
Variant	Line	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Total RAM Bit (Kb)	
Intel Arria 10 GX	GX 160	440	8,800	1,680	1,050	9,850	
	GX 220	587	11,740	2,703	1,690	13,430	
	GX 270	750	15,000	3,922	2,452	17,452	
	GX 320	891	17,820	4,363	2,727	20,547	
	GX 480	1,431	28,620	6,662	4,164	32,784	
	GX 570	1,800	36,000	8,153	5,096	41,096	
	GX 660	2,131	42,620	9,260	5,788	48,408	
	GX 900	2,423	48,460	15,017	9,386	57,846	
	GX 1150	2,713	54,260	20,774	12,984	67,244	
Intel Arria 10 GT	GT 900	2,423	48,460	15,017	9,386	57,846	
	GT 1150	2,713	54,260	20,774	12,984	67,244	
Intel Arria 10 SX	SX 160	440	8,800	1,680	1,050	9,850	
	SX 220	587	11,740	2,703	1,690	13,430	
	SX 270	750	15,000	3,922	2,452	17,452	
	SX 320	891	17,820	4,363	2,727	20,547	
	SX 480	1,431	28,620	6,662	4,164	32,784	
	SX 570	1,800	36,000	8,153	5,096	41,096	
	SX 660	2,131	42,620	9,260	5,788	48,408	



#### Table 20. Memory Standards Supported by the Hard Memory Controller

This table lists the overall capability of the hard memory controller. For specific details, refer to the External Memory Interface Spec Estimator and Intel Arria 10 Device Datasheet.

Memory Standard	Rate Support	Ping Pong PHY Support	Maximum Frequency (MHz)
DDR4 SDRAM	Quarter rate	Yes	1,067
		_	1,200
DDR3 SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	1,067
		_	1,067
DDR3L SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	933
		_	933
LPDDR3 SDRAM	Half rate	_	533
	Quarter rate	_	800

#### **Table 21.** Memory Standards Supported by the Soft Memory Controller

Memory Standard	Rate Support	Maximum Frequency (MHz)
RLDRAM 3 (11)	Quarter rate	1,200
QDR IV SRAM <sup>(11)</sup>	Quarter rate	1,067
QDR II SRAM	Full rate	333
	Half rate	633
QDR II+ SRAM	Full rate	333
	Half rate	633
QDR II+ Xtreme SRAM	Full rate	333
	Half rate	633

#### Table 22. Memory Standards Supported by the HPS Hard Memory Controller

The hard processor system (HPS) is available in Intel Arria 10 SoC devices only.

Memory Standard	Rate Support	Maximum Frequency (MHz)
DDR4 SDRAM	Half rate	1,200
DDR3 SDRAM	Half rate	1,067
DDR3L SDRAM	Half rate	933

<sup>(11)</sup> Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



#### **Related Information**

#### Intel Arria 10 Device Datasheet

Lists the memory interface performance according to memory interface standards, rank or chip select configurations, and Intel Arria 10 device speed grades.

## PCIe Gen1, Gen2, and Gen3 Hard IP

Intel Arria 10 devices contain PCIe hard IP that is designed for performance and ease-of-use:

- Includes all layers of the PCIe stack—transaction, data link and physical layers.
- Supports PCIe Gen3, Gen2, and Gen1 Endpoint and Root Port in x1, x2, x4, or x8 lane configuration.
- Operates independently from the core logic—optional configuration via protocol (CvP) allows the PCIe link to power up and complete link training in less than 100 ms while the Intel Arria 10 device completes loading the programming file for the rest of the FPGA.
- Provides added functionality that makes it easier to support emerging features such as Single Root I/O Virtualization (SR-IOV) and optional protocol extensions.
- Provides improved end-to-end datapath protection using ECC.
- Supports FPGA configuration via protocol (CvP) using PCIe at Gen3, Gen2, or Gen1 speed.

#### **Related Information**

PCS Features on page 30

## **Enhanced PCS Hard IP for Interlaken and 10 Gbps Ethernet**

#### **Interlaken Support**

The Intel Arria 10 enhanced PCS hard IP provides integrated Interlaken PCS supporting rates up to 25.8 Gbps per lane.

The Interlaken PCS is based on the proven functionality of the PCS developed for Intel's previous generation FPGAs, which demonstrated interoperability with Interlaken ASSP vendors and third-party IP suppliers. The Interlaken PCS is present in every transceiver channel in Intel Arria 10 devices.

#### **Related Information**

PCS Features on page 30

#### **10 Gbps Ethernet Support**

The Intel Arria 10 enhanced PCS hard IP supports 10GBASE-R PCS compliant with IEEE 802.3 10 Gbps Ethernet (10GbE). The integrated hard IP support for 10GbE and the 10 Gbps transceivers save external PHY cost, board space, and system power.



Figure 7. Device Chip Overview for Intel Arria 10 GX and GT Devices

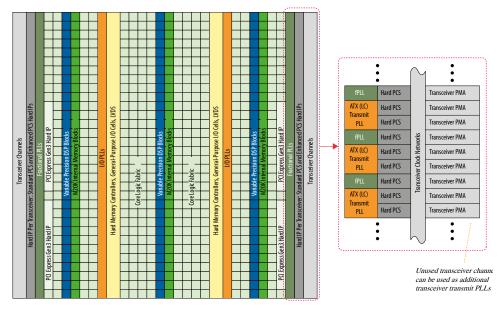
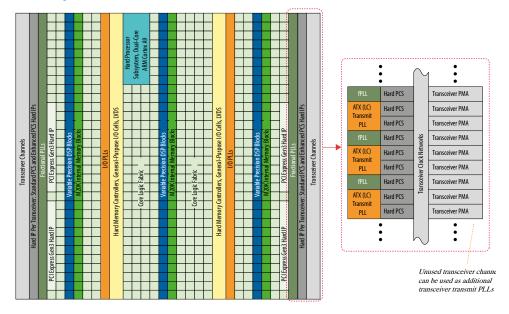


Figure 8. Device Chip Overview for Intel Arria 10 SX Devices



#### **PMA Features**

Intel Arria 10 transceivers provide exceptional signal integrity at data rates up to 25.8 Gbps. Clocking options include ultra-low jitter ATX PLLs (LC tank based), clock multiplier unit (CMU) PLLs, and fractional PLLs.



Each transceiver channel contains a channel PLL that can be used as the CMU PLL or clock data recovery (CDR) PLL. In CDR mode, the channel PLL recovers the receiver clock and data in the transceiver channel. Up to 80 independent data rates can be configured on a single Intel Arria 10 device.

Table 23. PMA Features of the Transceivers in Intel Arria 10 Devices

Feature	Capability	
Chip-to-Chip Data Rates	1 Gbps to 17.4 Gbps (Intel Arria 10 GX devices) 1 Gbps to 25.8 Gbps (Intel Arria 10 GT devices)	
Backplane Support	Drive backplanes at data rates up to 12.5 Gbps	
Optical Module Support	SFP+/SFP, XFP, CXP, QSFP/QSFP28, CFP/CFP2/CFP4	
Cable Driving Support	SFP+ Direct Attach, PCI Express over cable, eSATA	
Transmit Pre-Emphasis	4-tap transmit pre-emphasis and de-emphasis to compensate for system channel loss	
Continuous Time Linear Equalizer (CTLE)	Dual mode, high-gain, and high-data rate, linear receive equalization to compensate for system channel loss	
Decision Feedback Equalizer (DFE)	7-fixed and 4-floating tap DFE to equalize backplane channel loss in the presence of crosstalk and noisy environments	
Variable Gain Amplifier	Optimizes the signal amplitude prior to the CDR sampling and operates in fixed and adaptive modes	
Altera Digital Adaptive Parametric Tuning (ADAPT)	Fully digital adaptation engine to automatically adjust all link equalization parameters—including CTLE, DFE, and variable gain amplifier blocks—that provide optimal link margin without intervention from user logic	
Precision Signal Integrity Calibration Engine (PreSICE)	Hardened calibration controller to quickly calibrate all transceiver control parameters on power-up, which provides the optimal signal integrity and jitter performance	
Advanced Transmit (ATX) PLL	Low jitter ATX (LC tank based) PLLs with continuous tuning range to cover a wide range of standard and proprietary protocols	
Fractional PLLs	On-chip fractional frequency synthesizers to replace on-board crystal oscillators and reduce system cost	
Digitally Assisted Analog CDR	Superior jitter tolerance with fast lock time	
Dynamic Partial Reconfiguration	Allows independent control of the Avalon memory-mapped interface of each transceiver channel for the highest transceiver flexibility	
Multiple PCS-PMA and PCS- PLD interface widths	8-, 10-, 16-, 20-, 32-, 40-, or 64-bit interface widths for flexibility of deserialization width, encoding, and reduced latency	

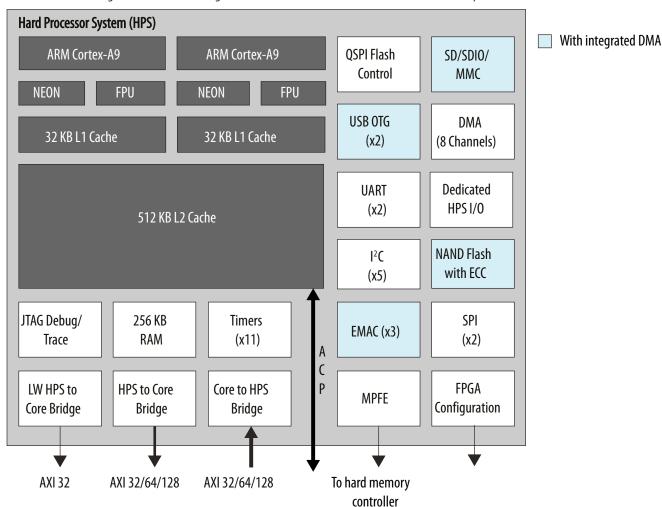
## **PCS Features**

This table summarizes the Intel Arria 10 transceiver PCS features. You can use the transceiver PCS to support a wide range of protocols ranging from 1 Gbps to 25.8 Gbps.



Figure 9. HPS Block Diagram

This figure shows a block diagram of the HPS with the dual ARM Cortex-A9 MPCore processor.



# **Key Advantages of 20-nm HPS**

The 20-nm HPS strikes a balance between enabling maximum software compatibility with 28-nm SoCs while still improving upon the 28-nm HPS architecture. These improvements address the requirements of the next generation target markets such as wireless and wireline communications, compute and storage equipment, broadcast and military in terms of performance, memory bandwidth, connectivity via backplane and security.



#### Table 24. **Improvements in 20 nm HPS**

This table lists the key improvements of the 20 nm HPS compared to the 28 nm HPS.

Advantages/ Improvements	Description		
Increased performance and overdrive capability	While the nominal processor frequency is 1.2 GHz, the 20 nm HPS offers an "overdrive" feature which enables a higher processor operating frequency. This requires a higher supply voltage value that is unique to the HPS and may require a separate regulator.		
Increased processor memory bandwidth and DDR4 support	Up to 64-bit DDR4 memory at 2,400 Mbps support is available for the processor. The hard memory controller for the HPS comprises a multi-port front end that manages connections to a single port memory controller. The multi-port front end allows logic core and the HPS to share ports and thereby the available bandwidth of the memory controller.		
Flexible I/O sharing	<ul> <li>An advanced I/O pin muxing scheme allows improved sharing of I/O between the HPS and the core logic. The following types of I/O are available for SoC:</li> <li>17 dedicated I/Os—physically located inside the HPS block and are not accessible to logic within the core. The 17 dedicated I/Os are used for HPS clock, resets, and interfacing with boot devices, QSPI, and SD/MMC.</li> <li>48 direct shared I/O—located closest to the HPS block and are ideal for high speed HPS peripherals such as EMAC, USB, and others. There is one bank of 48 I/Os that supports direct sharing where the 48 I/Os can be shared 12 I/Os at a time.</li> <li>Standard (shared) I/O—all standard I/Os can be shared by the PPS peripherals and any logic within the core. For designs where more than 48 I/Os are required to fully use all the peripherals in the HPS, these I/Os can be connected through the core logic.</li> </ul>		
EMAC core	Three EMAC cores are available in the HPS. The EMAC cores enable an application to support two redundant Ethernet connections; for example, backplane, or two EMAC cores for managing IEEE 1588 time stamp information while allowing a third EMAC core for debug and configuration. All three EMACs can potentially share the same time stamps, simplifying the 1588 time stamping implementation. A new serial time stamp interface allows core logic to access and read the time stamp values. The integrated EMAC controllers can be connected to external Ethernet PHY through the provided MDIO or I <sup>2</sup> C interface.		
On-chip memory	The on-chip memory is updated to 256 KB support and can support larger data sets and real time algorithms.		
ECC enhancements	Improvements in L2 Cache ECC management allow identification of errors down to the address level. ECC enhancements also enable improved error injection and status reporting via the introduction of new memory mapped access to syndrome and data signals.		
HPS to FPGA Interconnect Backbone	Although the HPS and the Logic Core can operate independently, they are tightly coupled via a high-bandwidth system interconnect built from high-performance ARM AMBA AXI bus bridges. IP bus masters in the FPGA fabric have access to HPS bus slaves via the FPGA-to-HPS interconnect. Similarly, HPS bus masters have access to bus slaves in the core fabric via the HPS-to-FPGA bridge. Both bridges are AMBA AXI-3 compliant and support simultaneous read and write transactions. Up to three masters within the core fabric can share the HPS SDRAM controller with the processor. Additionally, the processor can be used to configure the core fabric under program control via a dedicated 32-bit configuration port.		
FPGA configuration and HPS booting	The FPGA fabric and HPS in the SoCs are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power.  You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility.		
Security	New security features have been introduced for anti-tamper management, secure boot, encryption (AES), and authentication (SHA).		



#### Features of the HPS

The HPS has the following features:

- 1.2-GHz, dual-core ARM Cortex-A9 MPCore processor with up to 1.5-GHz via overdrive
  - ARMv7-A architecture that runs 32-bit ARM instructions, 16-bit and 32-bit
     Thumb instructions, and 8-bit Java byte codes in Jazelle style
  - Superscalar, variable length, out-of-order pipeline with dynamic branch prediction
  - Instruction Efficiency 2.5 MIPS/MHz, which provides total performance of 7500 MIPS at 1.5 GHz
- Each processor core includes:
  - 32 KB of L1 instruction cache, 32 KB of L1 data cache
  - Single- and double-precision floating-point unit and NEON media engine
  - CoreSight debug and trace technology
  - Snoop Control Unit (SCU) and Acceleration Coherency Port (ACP)
- 512 KB of shared L2 cache
- 256 KB of scratch RAM
- Hard memory controller with support for DDR3, DDR4 and optional error correction code (ECC) support
- Multiport Front End (MPFE) Scheduler interface to the hard memory controller
- 8-channel direct memory access (DMA) controller
- QSPI flash controller with SIO, DIO, QIO SPI Flash support
- NAND flash controller (ONFI 1.0 or later) with DMA and ECC support, updated to support 8 and 16-bit Flash devices and new command DMA to offload CPU for fast power down recovery
- Updated SD/SDIO/MMC controller to eMMC 4.5 with DMA with CE-ATA digital command support
- 3 10/100/1000 Ethernet media access control (MAC) with DMA
- 2 USB On-the-Go (OTG) controllers with DMA
- 5 I<sup>2</sup>C controllers (3 can be used by EMAC for MIO to external PHY)
- 2 UART 16550 Compatible controllers
- 4 serial peripheral interfaces (SPI) (2 Master, 2 Slaves)
- 62 programmable general-purpose I/Os, which includes 48 direct share I/Os that allows the HPS peripherals to connect directly to the FPGA I/Os
- 7 general-purpose timers
- 4 watchdog timers
- Anti-tamper, Secure Boot, Encryption (AES) and Authentication (SHA)



#### **System Peripherals and Debug Access Port**

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

#### **HPS-FPGA AXI Bridges**

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA) Advanced eXtensible Interface (AXI $^{\text{\tiny M}}$ ) specifications, consist of the following bridges:

- FPGA-to-HPS AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA Avalon/AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows
  the HPS to issue transactions to soft peripherals in the FPGA fabric. This bridge is
  primarily used for control and status register (CSR) accesses to peripherals in the
  FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

#### **HPS SDRAM Controller Subsystem**

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

The HPS SDRAM controller supports up to 3 masters (command ports), 3x 64-bit read data ports and 3x 64-bit write data ports.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features.



## **FPGA Configuration and HPS Booting**

The FPGA fabric and HPS in the SoC FPGA must be powered at the same time. You can reduce the clock frequencies or gate the clocks to reduce dynamic power.

Once powered, the FPGA fabric and HPS can be configured independently thus providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or
  partially reconfigure the FPGA fabric at any time under software control. The HPS
  can also configure other FPGAs on the board through the FPGA configuration
  controller.
- Configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

## **Hardware and Software Development**

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer system integration tool in the Intel Quartus Prime software.

For software development, the ARM-based SoC FPGA devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Intel SoC FPGAs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux\*, VxWorks\*, and other operating systems are available for the SoC FPGAs. For more information on the operating systems support availability, contact the Intel FPGA sales team.

You can begin device-specific firmware and software development on the Intel SoC FPGA Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

## **Dynamic and Partial Reconfiguration**

The Intel Arria 10 devices support dynamic and partial reconfiguration. You can use dynamic and partial reconfiguration simultaneously to enable seamless reconfiguration of both the device core and transceivers.

## **Dynamic Reconfiguration**

You can reconfigure the PMA and PCS blocks while the device continues to operate. This feature allows you to change the data rates, protocol, and analog settings of a channel in a transceiver bank without affecting on-going data transfer in other transceiver banks. This feature is ideal for applications that require dynamic multiprotocol or multirate support.

## **Partial Reconfiguration**

Using partial reconfiguration, you can reconfigure some parts of the device while keeping the device in operation.



Date	Version	Changes
December 2015	2015.12.14	Updated the number of M20K memory blocks for Arria 10 GX 660 from 2133 to 2131 and corrected the total RAM bit from 48,448 Kb to 48,408 Kb.
		Corrected the number of DSP blocks for Arria 10 GX 660 from 1688 to 1687 in the table listing floating-point arithmetic resources.
November 2015	2015.11.02	• Updated the maximum resources for Arria 10 GX 220, GX 320, GX 480, GX 660, SX 220, SX 320, SX 480, and SX 660.
		Updated resource count for Arria 10 GX 320, GX 480, GX 660, SX 320, SX 480, a SX 660 devices in <b>Number of Multipliers in Intel Arria 10 Devices</b> table.
		<ul> <li>Updated the available options for Arria 10 GX, GT, and SX.</li> <li>Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.</li> </ul>
June 2015	2015.06.15	Corrected label for Intel Arria 10 GT product lines in the vertical migration figure.
May 2015	2015.05.15	Corrected the DDR3 half rate and quarter rate maximum frequencies in the table that lists the memory standards supported by the Intel Arria 10 hard memory controller.
May 2015	2015.05.04	Added support for 13.5G JESD204b in the Summary of Features table.  Added support for 13.5G JESD204b in the Summary of Features table.
		Added a link to Arria 10 GT Channel Usage in the Arria 10 GT Package Plan topic.
		Added a note to the table, Maximum Resource Counts for Arria 10 GT devices.
		Updated the power requirements of the transceivers in the Low Power Serial Transceivers topic.
January 2015	2015.01.23	Added floating point arithmetic features in the Summary of Features table.
		Updated the total embedded memory from 38.38 megabits (Mb) to 65.6 Mb.
		Updated the table that lists the memory standards supported by Intel Arria 10 devices.
		<ul> <li>Removed support for DDR3U, LPDDR3 SDRAM, RLDRAM 2, and DDR2.</li> <li>Moved RLDRAM 3 support from hard memory controller to soft memory controller. RLDRAM 3 support uses hard PHY with soft memory controller.</li> </ul>
		Added soft memory controller support for QDR IV.
		Updated the maximum resource count table to include the number of hard memory controllers available in each device variant.
		Updated the transceiver PCS data rate from 12.5 Gbps to 12 Gbps.
		Updated the max clock rate of PS, FPP x8, FPP x16, and Configuration via HPS from 125 MHz to 100 MHz.
		Added a feature for fractional synthesis PLLs: PLL cascading.
		Updated the HPS programmable general-purpose I/Os from 54 to 62.
September 2014	2014.09.30	Corrected the 3 V I/O and LVDS I/O counts for F35 and F36 packages of Arria 10 GX.
		Corrected the 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 570 and 660.
		Removed 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 900 and 1150. The NF40 package is not available for Arria 10 GX 900 and 1150.
		continued

#### Intel® Arria® 10 Device Overview

#### A10-OVERVIEW | 2018.04.09



Date	Version	Changes
August 2014	2014.08.18	Updated Memory (Kb) M20K maximum resources for Arria 10 GX 660 devices from 42,660 to 42,620.
		Added GPIO columns consisting of LVDS I/O Bank and 3V I/O Bank in the Package Plan table.
		Added how to use memory interface clock frequency higher than 533 MHz in the I/O vertical migration.
		Added information to clarify that RLDRAM3 support uses hard PHY with soft memory controller.
		Added variable precision DSP blocks support for floating-point arithmetic.
June 2014	2014.06.19	Updated number of dedicated I/Os in the HPS block to 17.
February 2014	2014.02.21	Updated transceiver speed grade options for GT devices in Figure 2.
February 2014	2014.02.06	Updated data rate for Arria 10 GT devices from 28.1 Gbps to 28.3 Gbps.
December 2013	2013.12.10	Updated the HPS memory standards support from LPDDR2 to LPDDR3.     Updated HPS block diagram to include dedicated HPS I/O and FPGA Configuration blocks as well as repositioned SD/SDIO/MMC, DMA, SPI and NAND Flash with ECC blocks .
December 2013	2013.12.02	Initial release.